

Surface Mount Schottky Power Rectifier

SMB Power Surface Mount Package

SS26T3G, NRVBSS26T3G, NRVBSS26NT3G, SRVBSS26NT3G

... employing the Schottky Barrier principle in a metal-to-silicon power rectifier. Features epitaxial construction with oxide passivation and metal overlay contact. Ideally suited for low voltage, high frequency switching power supplies; free wheeling diodes and polarity protection diodes.

Features

- Compact Package with J-Bend Leads Ideal for Automated Handling
- Highly Stable Oxide Passivated Junction
- Guardring for Overvoltage Protection
- Low Forward Voltage Drop
- NRVB Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable*
- These are Pb-Free Devices

Mechanical Characteristics:

- Case: Molded Epoxy
- Epoxy Meets UL 94, V-O at 0.125 in
- Weight: 95 mg (approximately)
- · Cathode Polarity Band
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 Seconds
- Available in 12 mm Tape, 2500 Units per 13" Reel, Add "T3" Suffix to Part Number

1

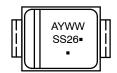
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- ESD Ratings: Human Body Model = 3B Machine Model = C
- Marking: SS26

SCHOTTKY BARRIER RECTIFIER 2.0 AMPERES 60 VOLTS



SMB CASE 403A

MARKING DIAGRAM



SS26 = Specific Device Code A = Assembly Location**

Y = Year WW = Work Week • Pb-Free Package

(Note: Microdot may be in either location)

**The Assembly Location code (A) is front side optional. In cases where the Assembly Location is stamped in the package bottom (molding ejecter pin), the front side assembly code may be blank.

ORDERING INFORMATION

Device	Package	Shipping [†]
SS26T3G	SMB (Pb-Free)	2500 / Tape & Reel
NRVBSS26T3G*	SMB (Pb-Free)	2500 / Tape & Reel
NRVBSS26NT3G*	SMB (Pb-Free)	2500 / Tape & Reel
SRVBSS26NT3G*	SMB (Pb-Free)	2500 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

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MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	60	V
Average Rectified Forward Current (At Rated V_R , $T_L = 95^{\circ}C$)	lo	2.0	Α
Non-Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions Halfwave, Single Phase, 60 Hz)	I _{FSM}	40	Α
Storage/Operating Case Temperature	T _{stg} , T _C	−55 to +150	°C
Operating Junction Temperature	T_J	-55 to +150	°C
Voltage Rate of Change (Rated V_R , T_J = 25°C)	dv/dt	10,000	V/μs

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL CHARACTERISTICS

Characteristic	Symbol	Value	Unit
Thermal Resistance – Junction–to–Lead (Note 1) Thermal Resistance – Junction–to–Ambient (Note 2)	$egin{array}{l} {\sf R}_{ heta {\sf J} {\sf A}} \end{array}$	24 80	°C/W

^{1.} Mounted with minimum recommended pad size, PC Board FR4.

ELECTRICAL CHARACTERISTICS

		Value		
Characteristic	Symbol	T _J = 25°C	T _J = 125°C	Unit
Maximum Instantaneous Forward Voltage (Note 3) $ \begin{aligned} &(i_F = 1.0 \text{ A}) \\ &(i_F = 2.0 \text{ A}) \end{aligned} $	VF	0.51 0.63	0.475 0.55	V
Maximum Instantaneous Reverse Current (Note 3) (V _R = 60 V)	I _R	0.2	20	mA

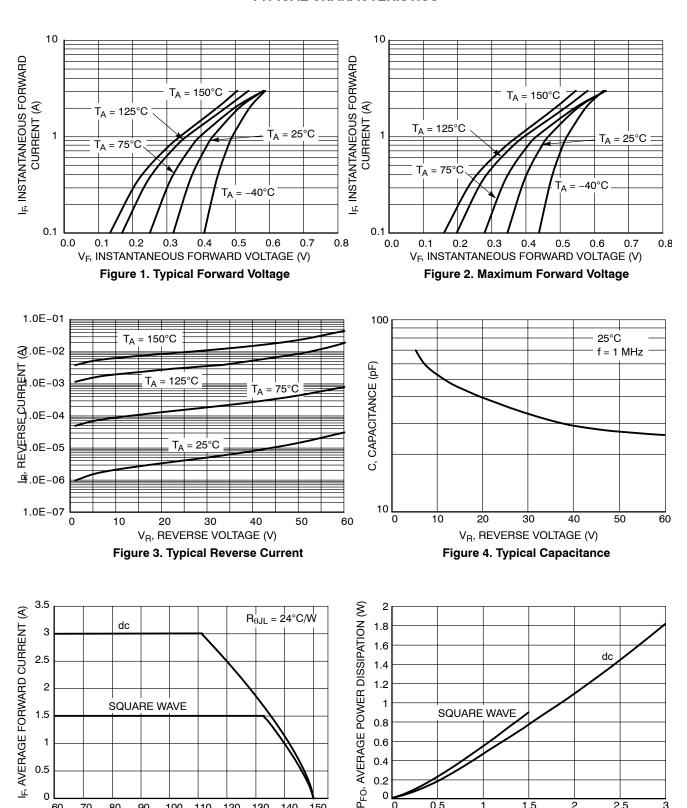
Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

^{2. 1} inch square pad size (1 x 0.5 inch for each lead) on FR4 board.

^{3.} Pulse Test: Pulse Width \leq 250 μ s, Duty Cycle \leq 2.0%.

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TYPICAL CHARACTERISTICS



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1.5

I_O, AVERAGE FORWARD CURRENT (A)

Figure 6. Forward Power Dissipation

120

60

70

90

100

110 T_L, LEAD TEMPERATURE (°C)

Figure 5. Current Derating - Junction to Lead

130

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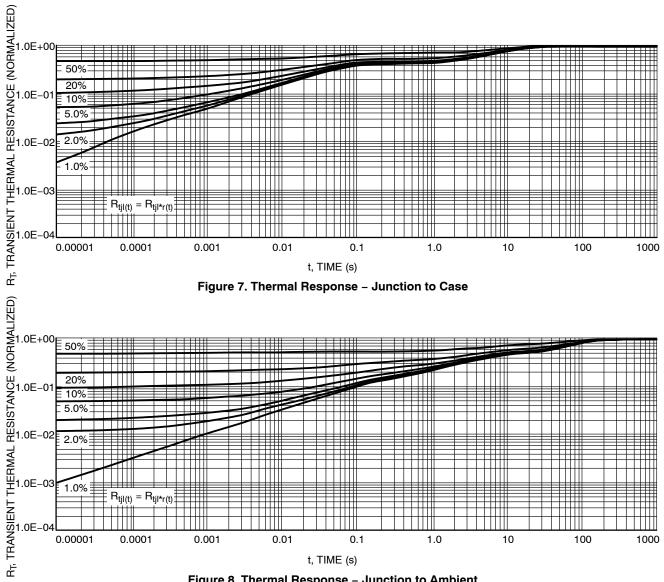


Figure 7. Thermal Response - Junction to Case

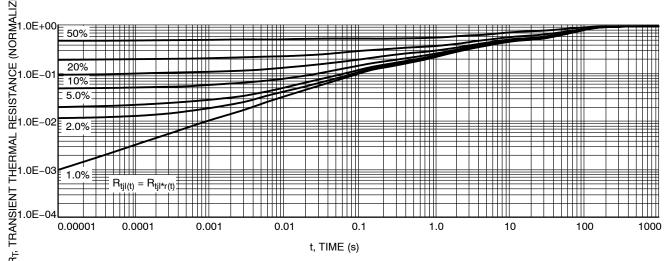


Figure 8. Thermal Response - Junction to Ambient





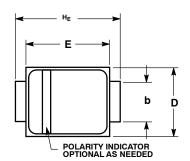


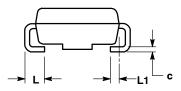
SMB CASE 403A-03 **ISSUE J**

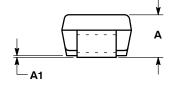
DATE 19 JUL 2012

Polarity Band

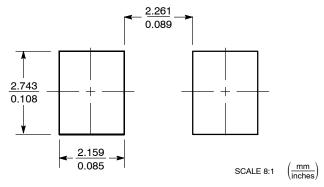
SCALE 1:1 Non-Polarity Band







SOLDERING FOOTPRINT*



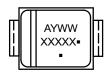
*For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: INCL.
- CONTROLLING DIMENSION: INCH.
 DIMENSION b SHALL BE MEASURED WITHIN DIMENSION L1.

	MILLIMETERS				INCHES	
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	1.95	2.30	2.47	0.077	0.091	0.097
A1	0.05	0.10	0.20	0.002	0.004	0.008
b	1.96	2.03	2.20	0.077	0.080	0.087
С	0.15	0.23	0.31	0.006	0.009	0.012
D	3.30	3.56	3.95	0.130	0.140	0.156
E	4.06	4.32	4.60	0.160	0.170	0.181
HE	5.21	5.44	5.60	0.205	0.214	0.220
L	0.76	1.02	1.60	0.030	0.040	0.063
L1		0.51 REF			0.020 REF	

GENERIC MARKING DIAGRAM*





Polarity Band

Non-Polarity Band

XXXXX = Specific Device Code = Assembly Location

= Year WW = Work Week = Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.

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